

EXPRES MAIL LABEL NO: EL 579 029 877 US
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PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD

AND LEADFRAME FOR MAKING THE PACKAGE

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5 This application is a CON of 10/171,702, filed on 6/14/2002, now Patent No 6630728
which is a CON of 09/615,107, filed on 7/13/2000, now Patent No 6433277
FIELD OF THE INVENTION which is a CON of 09/103,760, filed on 6/24/1998, now
Patent No 6,143,981.

The present invention is directed toward an improved plastic package for an integrated circuit die,
and a method of making such a package.

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BACKGROUND OF THE INVENTION

Integrated circuit die are conventionally enclosed
in plastic packages that provide protection from
hostile environments and enable electrical
15 interconnection between the integrated circuit die and
printed circuit boards. The elements of such a package
include a metal leadframe, an integrated circuit die,
bonding material to attach the integrated circuit die
to the leadframe, bond wires which electrically connect
20 pads on the integrated circuit die to individual leads
of the leadframe, and a hard plastic encapsulant
material which covers the other components and forms
the exterior of the package.

The leadframe is the central supporting structure
25 of such a package. A portion of the leadframe is

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